

FIG. 1

ATTY DKT. NO.: AMAT/7669.P1/CMP/ECP/RKK
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: MULTI-CHEMISTRY PLATING SYSTEM
INVENTOR: MICHAEL X. YANG, ET AL.
EXPRESS MAIL No.: EV351031813US PAGE 2 OF 27

PAGE 2 OF 27

2/27

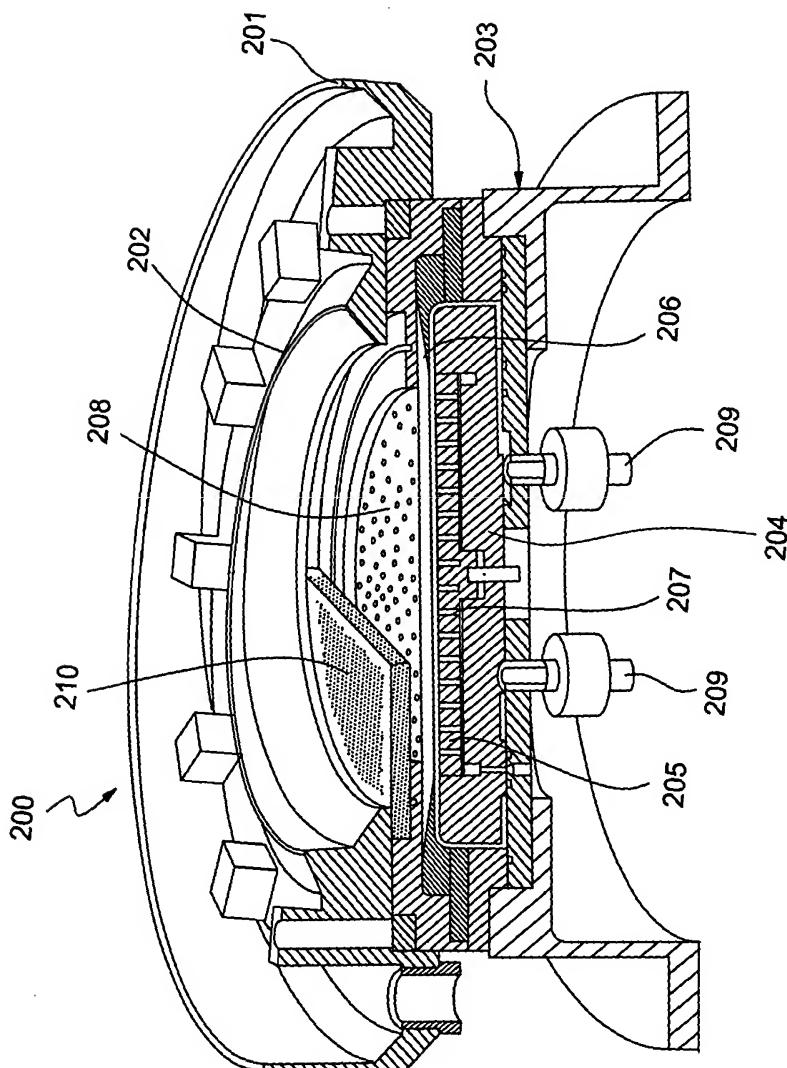


FIG. 2

3/27

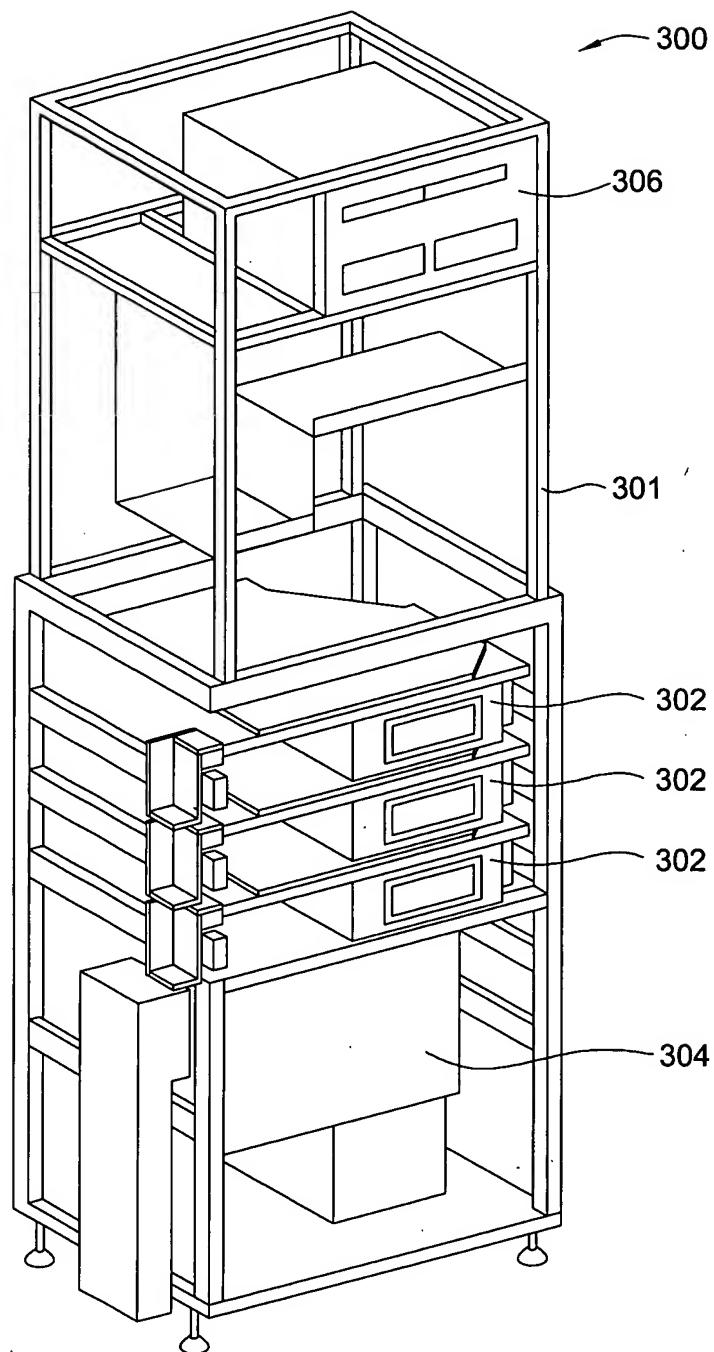
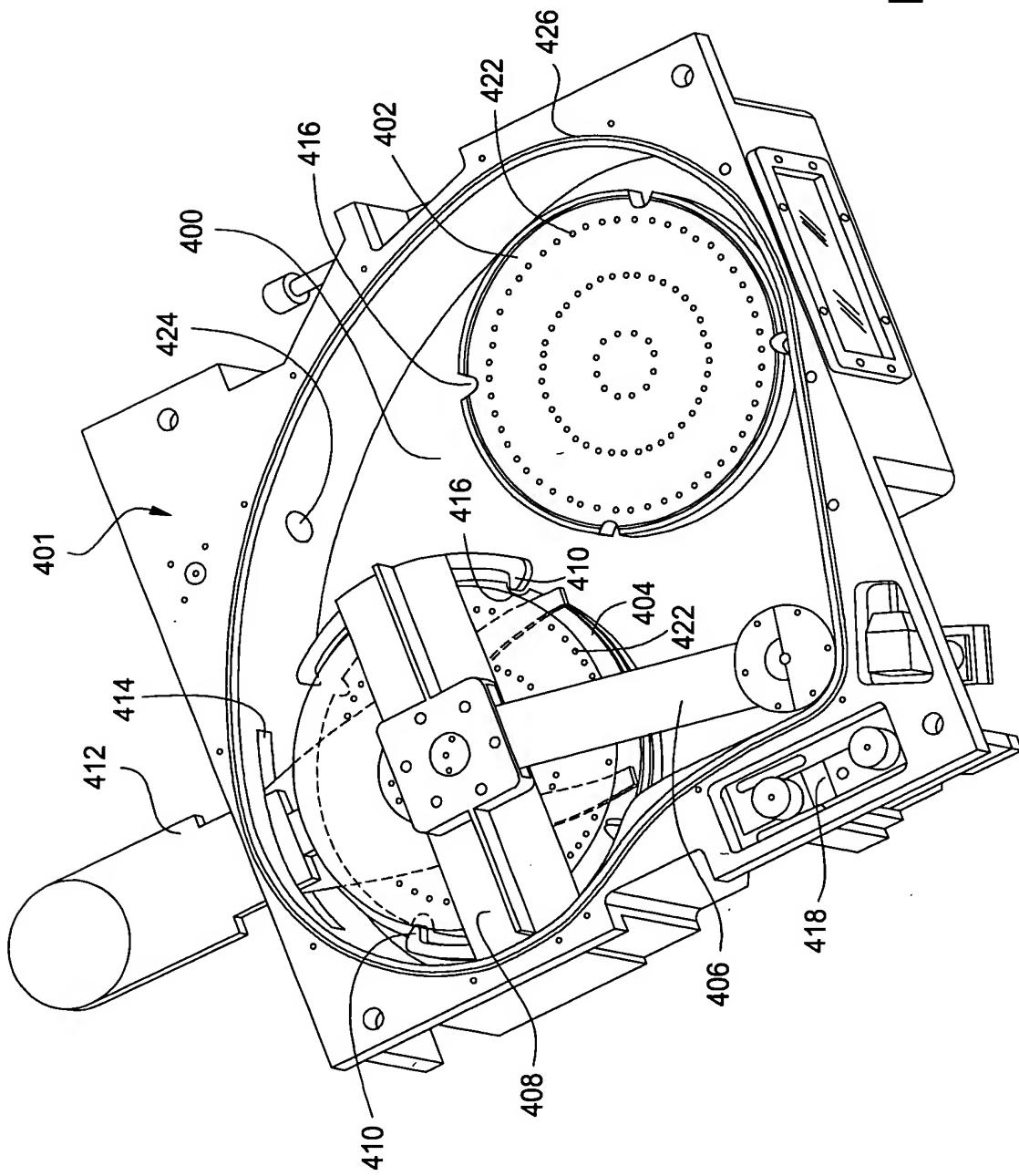


FIG. 3

4/27

FIG. 4



5/27

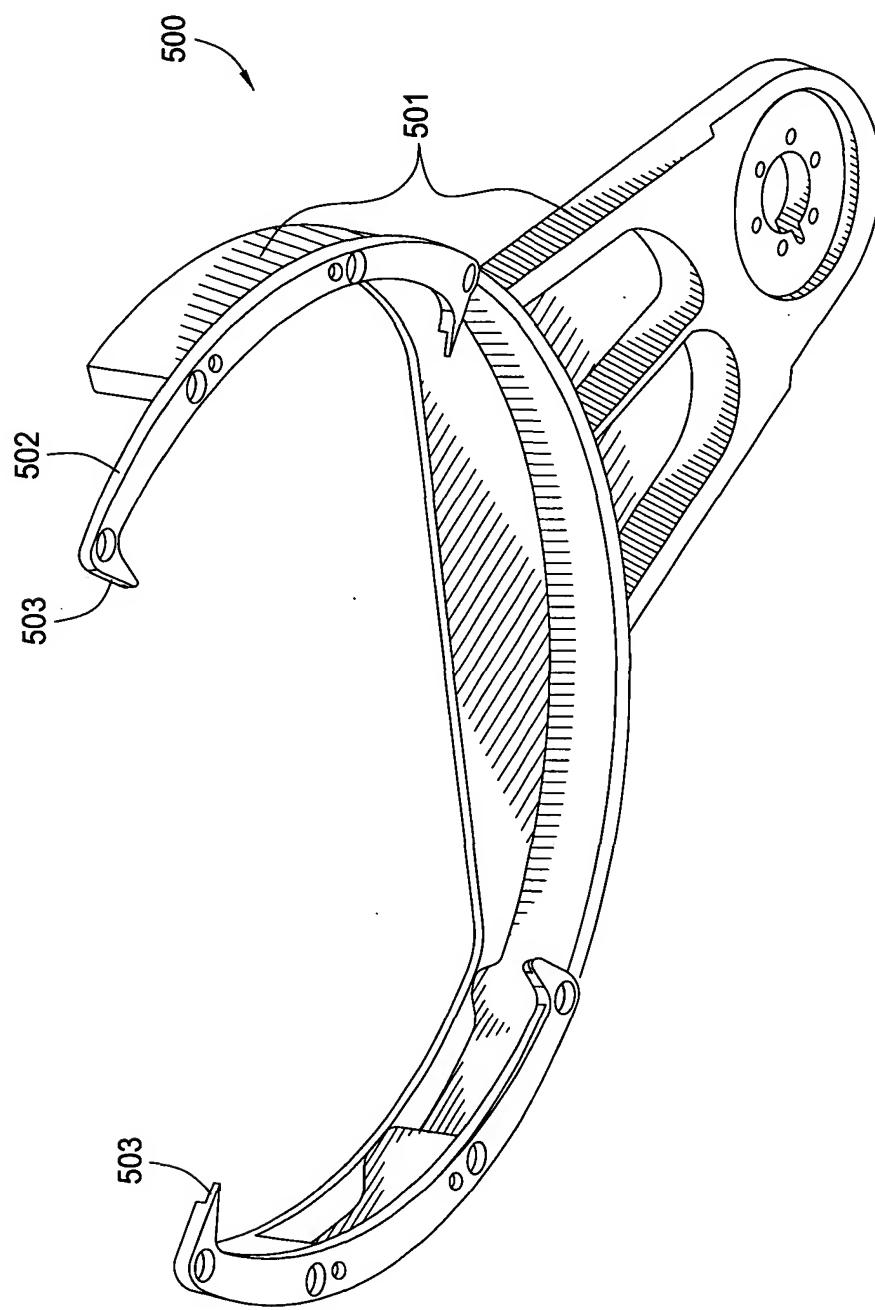


FIG. 5

6/27

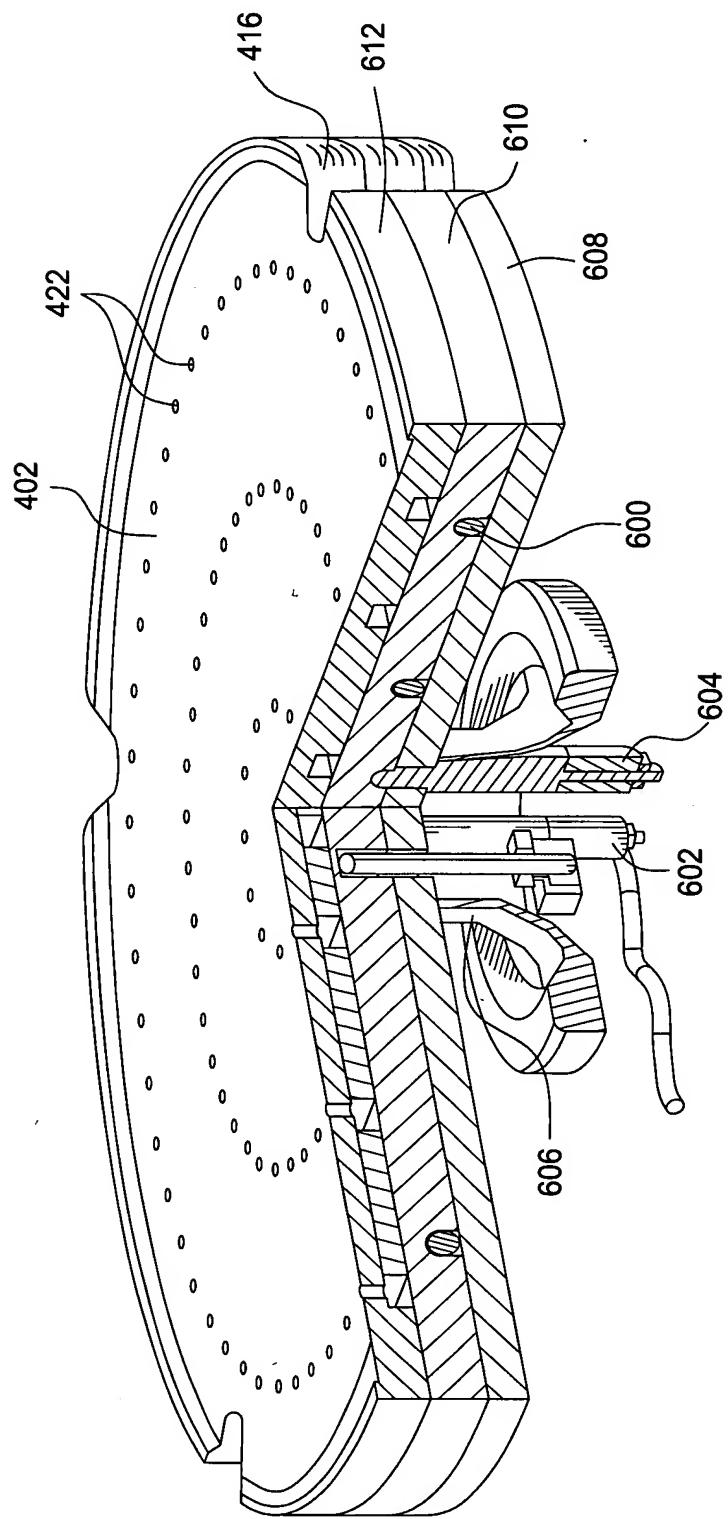


FIG. 6

7/27

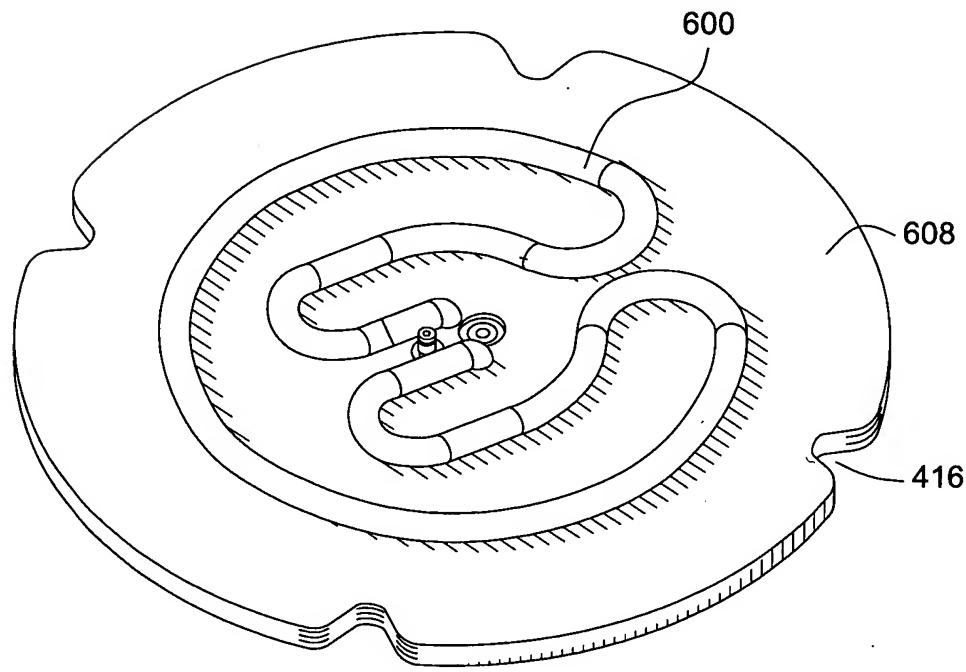


FIG. 7

8/27

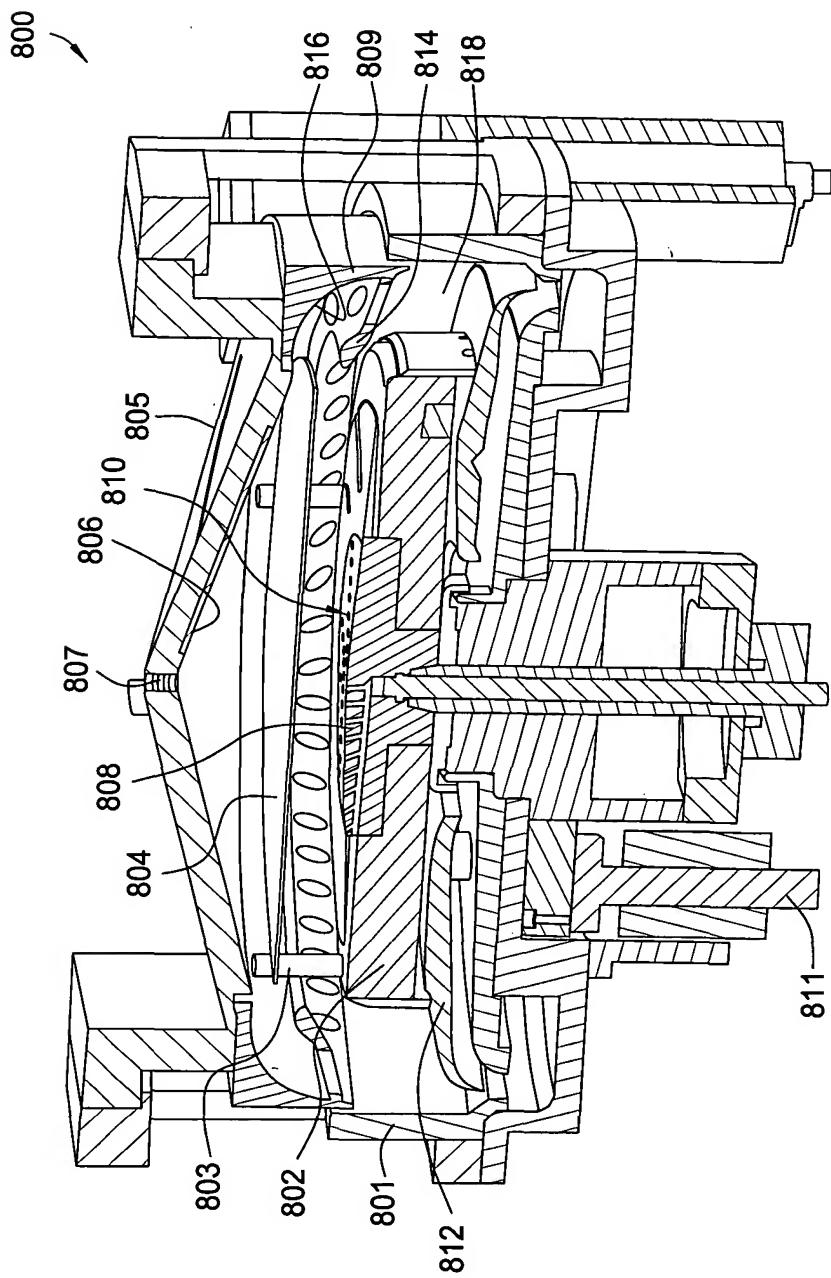


FIG. 8

9/27

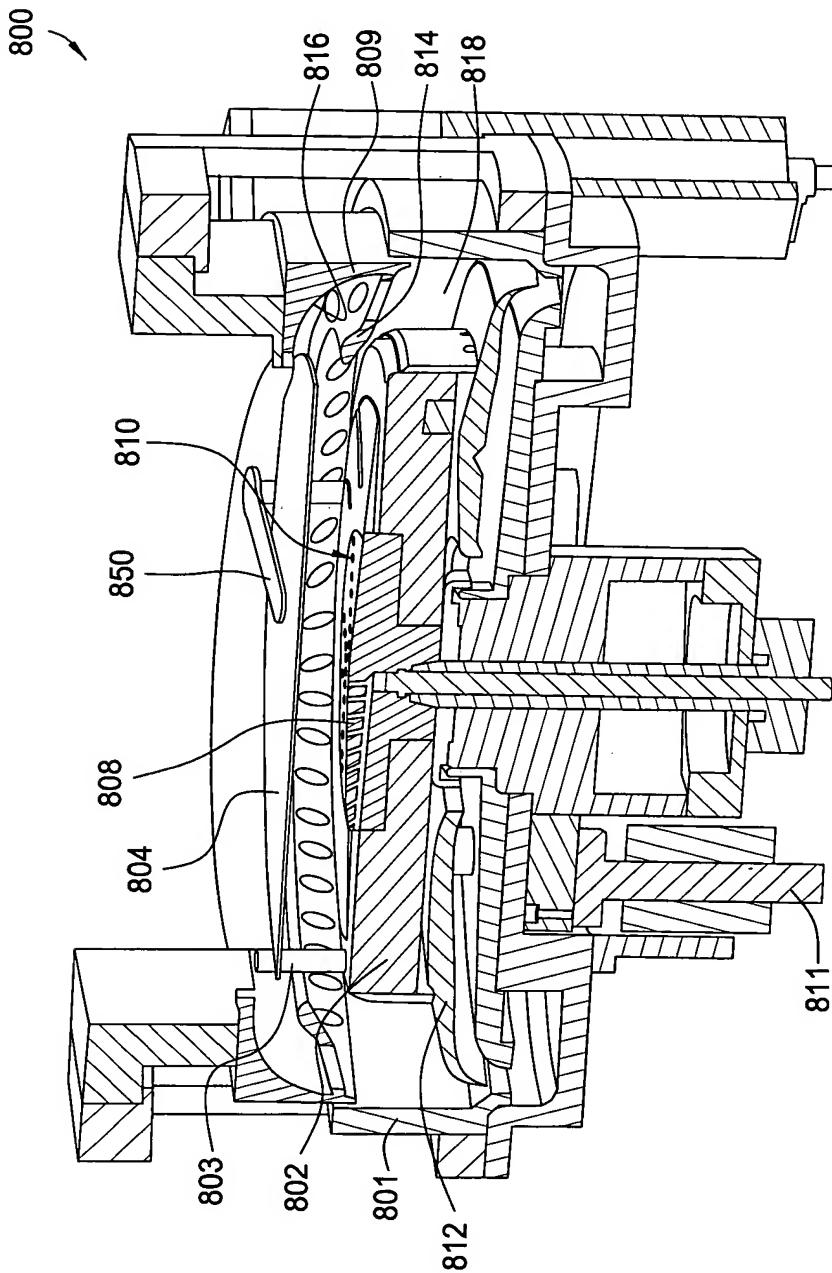


FIG. 9

10/27

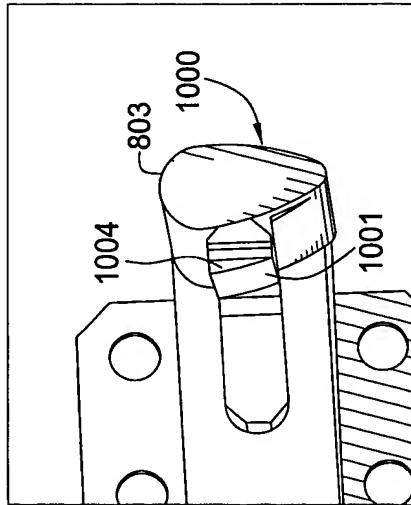


FIG. 10B

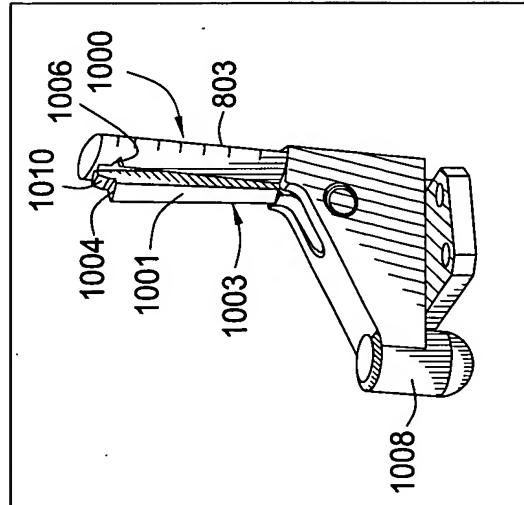


FIG. 10D

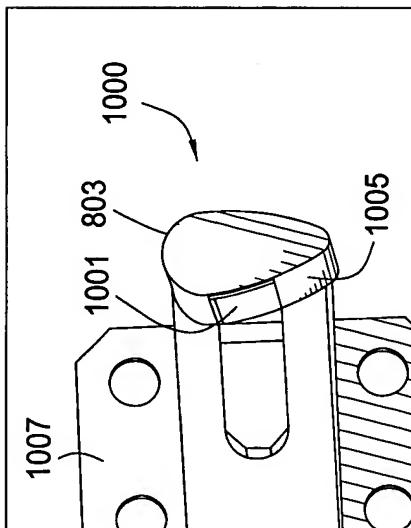


FIG. 10A

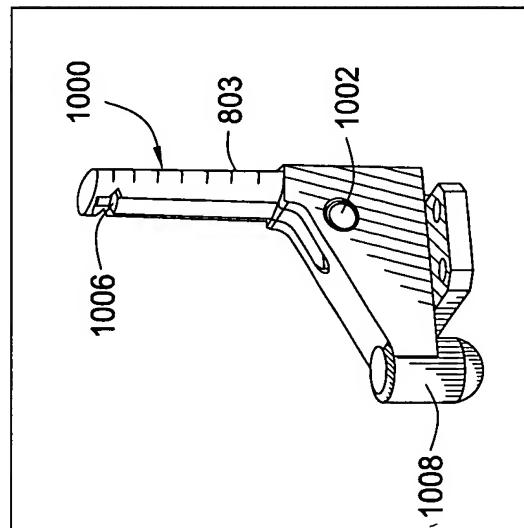
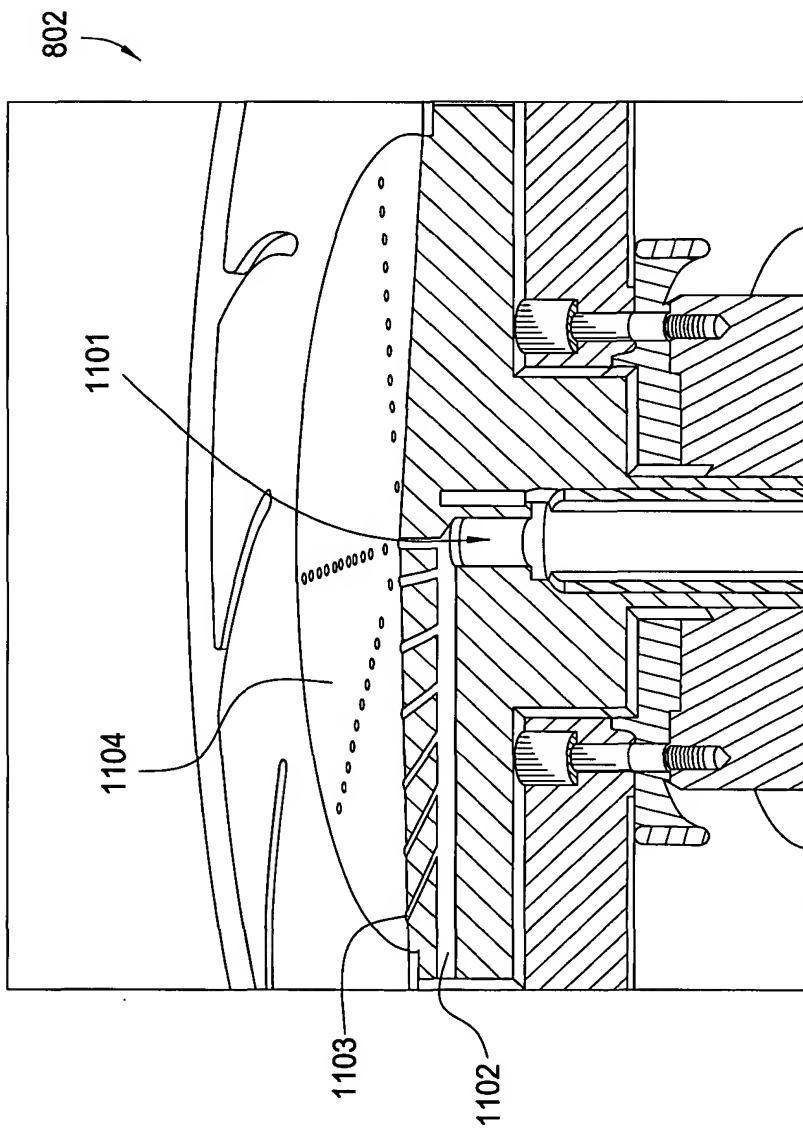


FIG. 10C

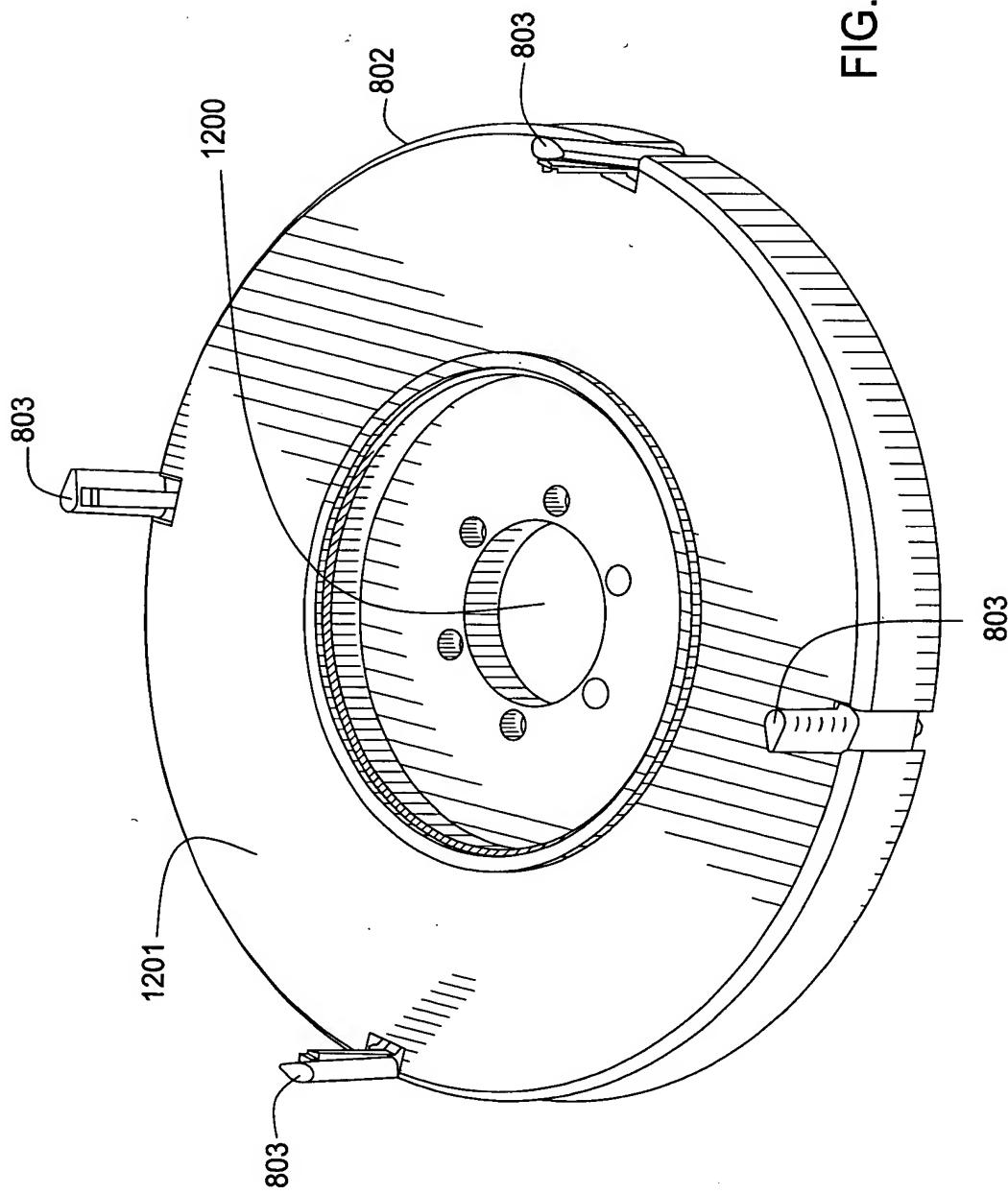
11/27

FIG. 11



12/27

FIG. 12



13/27

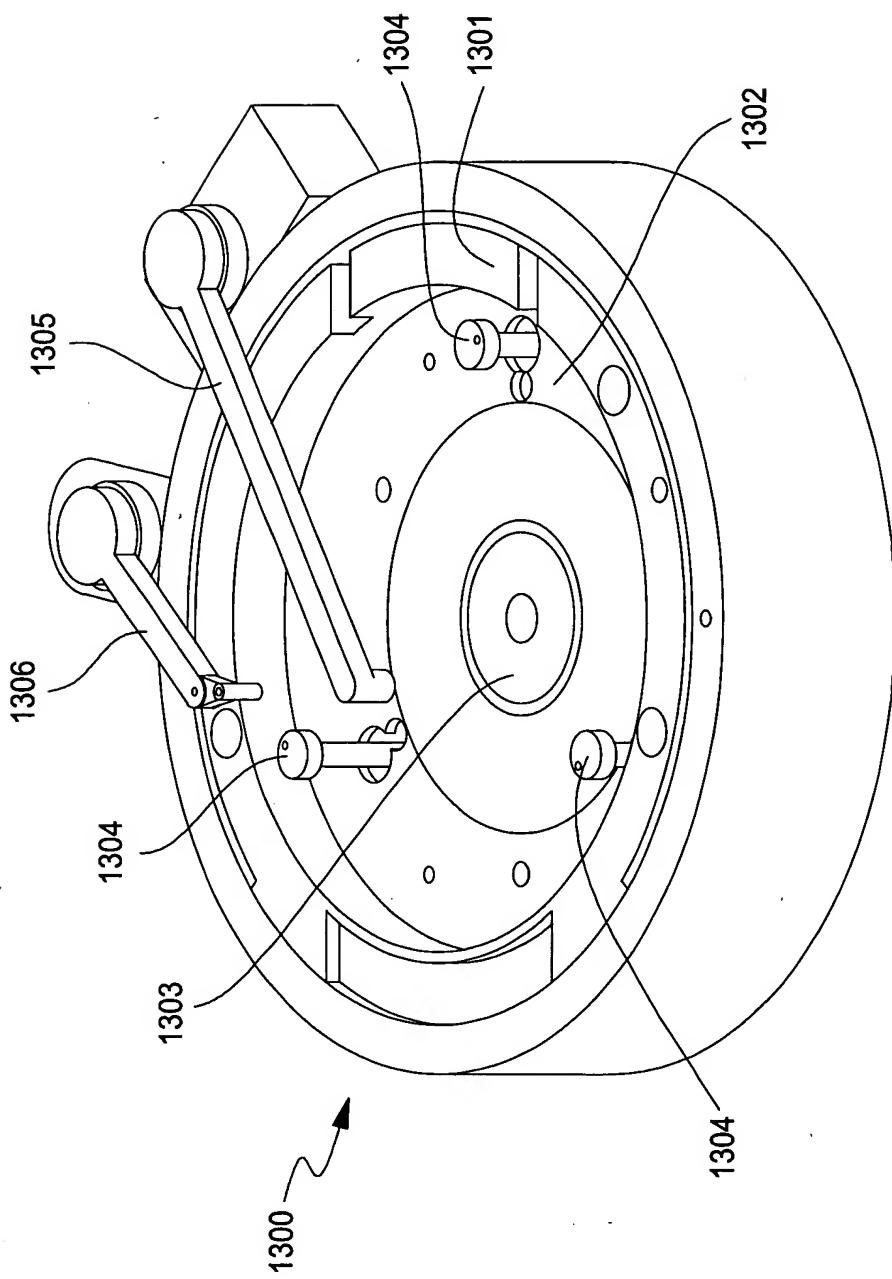


FIG. 13

14/27

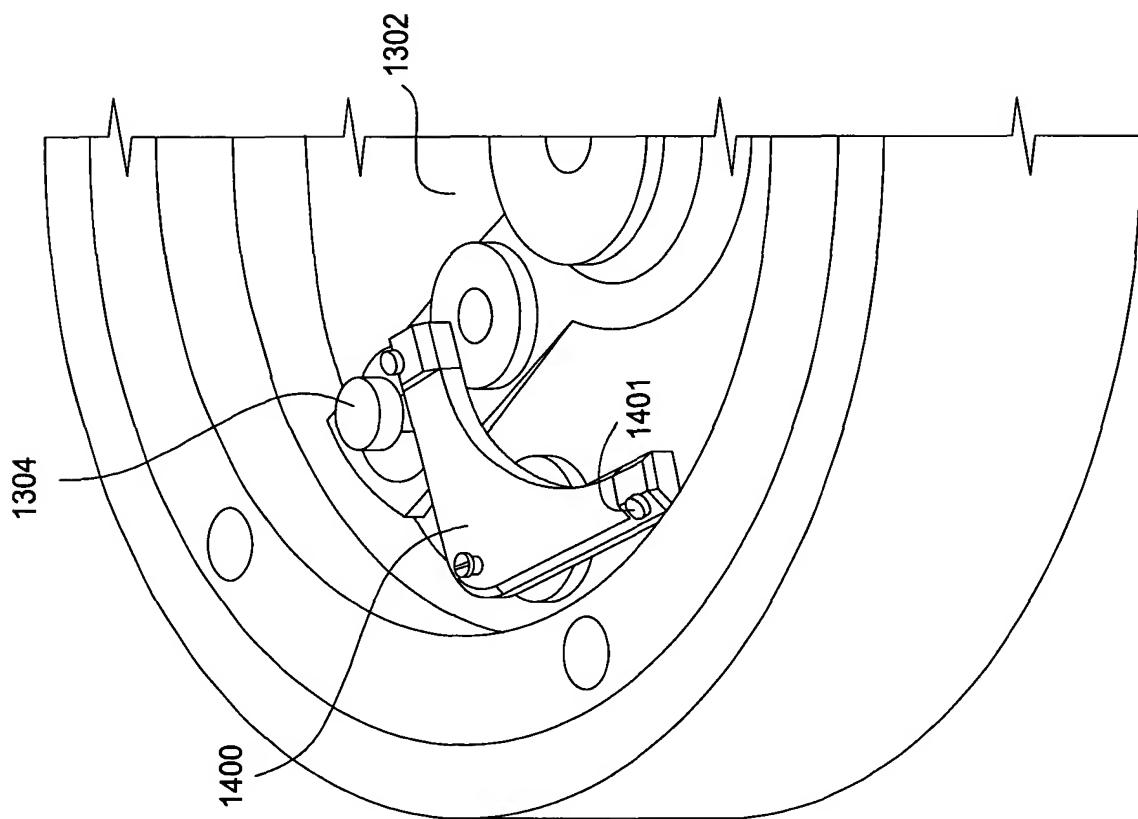


FIG. 14

15/27

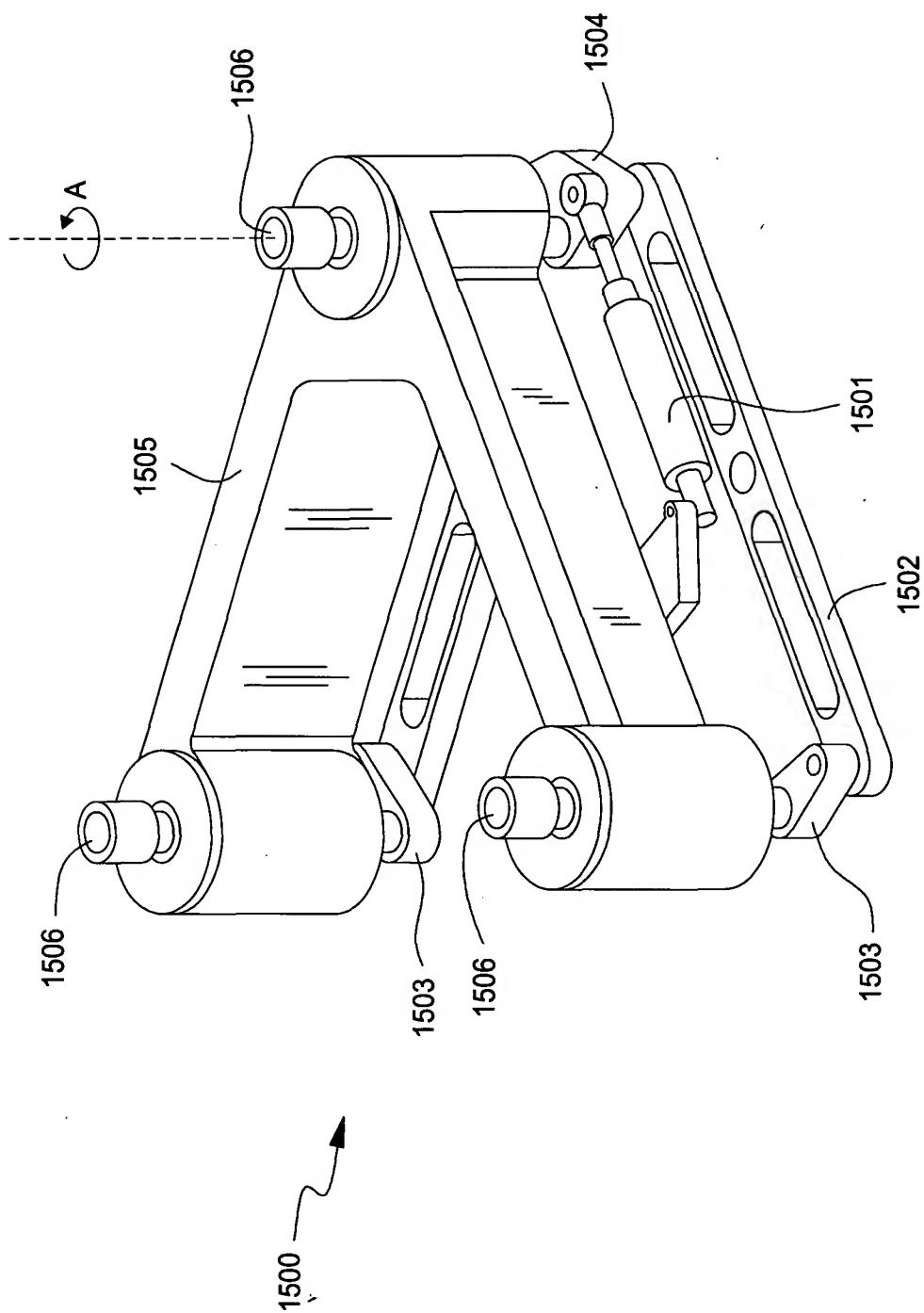


FIG. 15

16/27

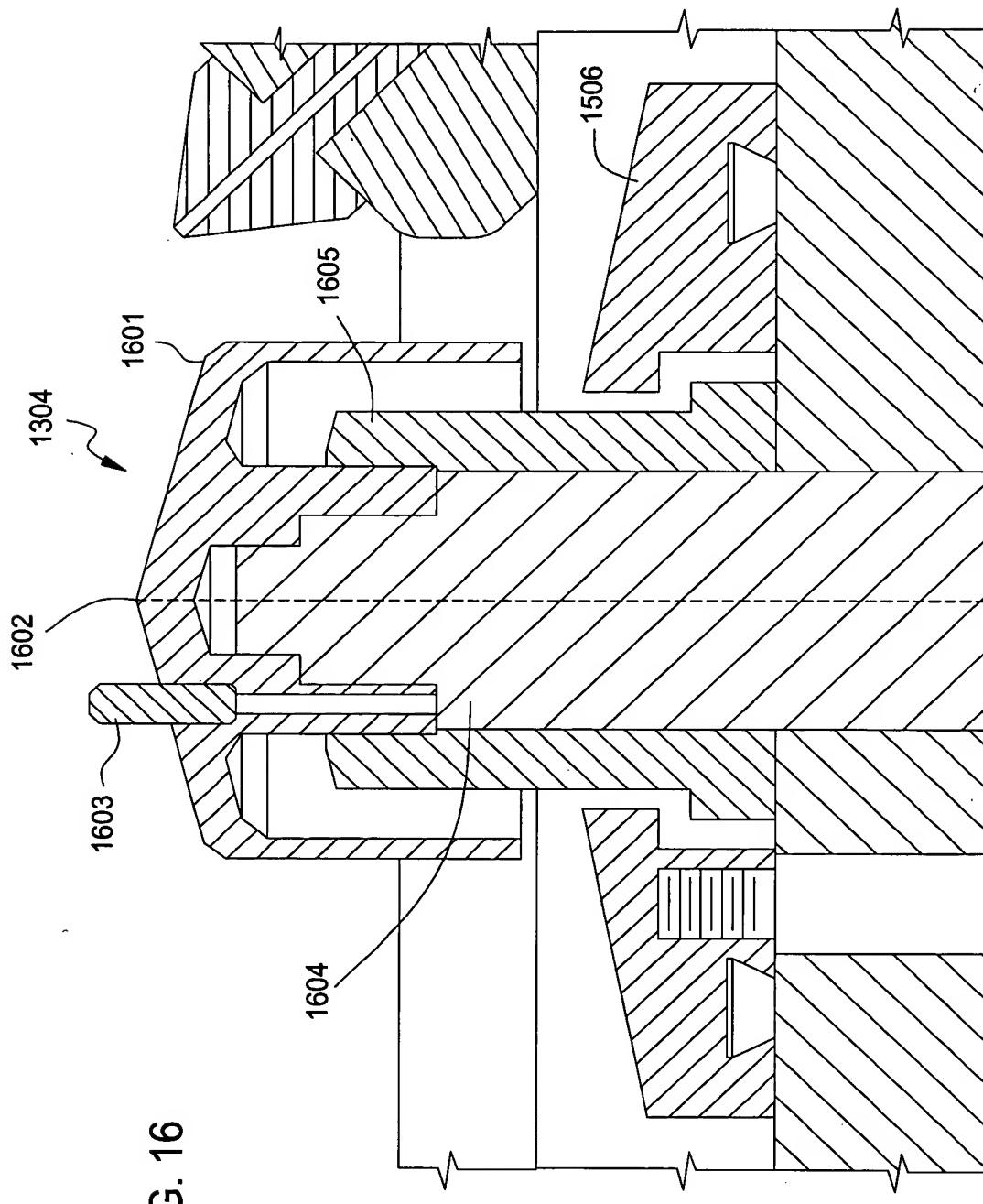


FIG. 16

17/27

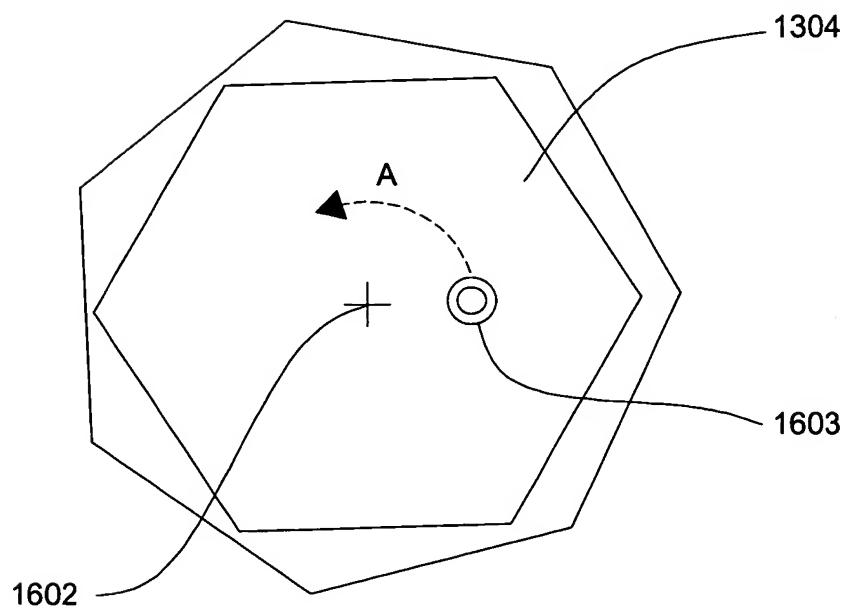
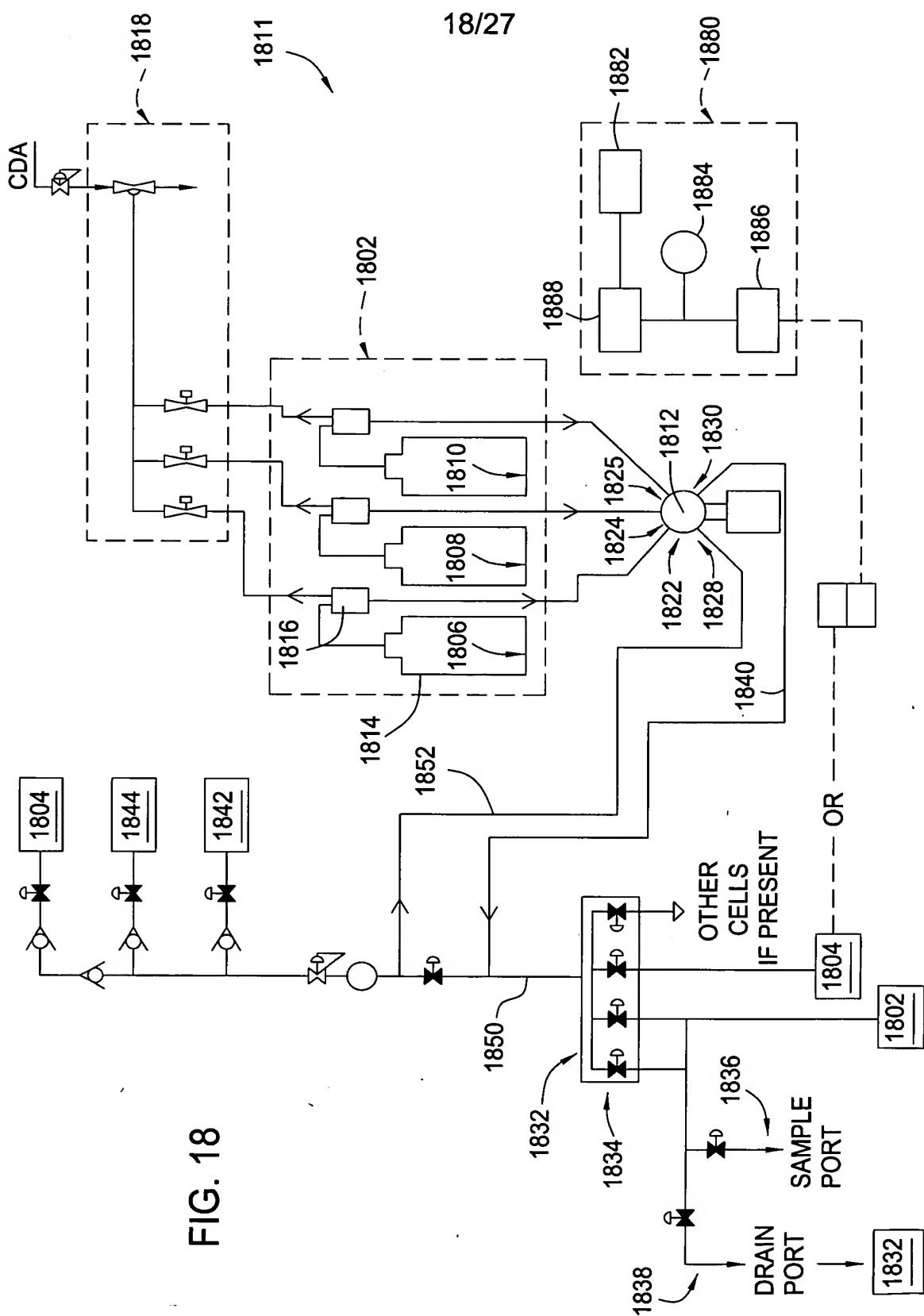


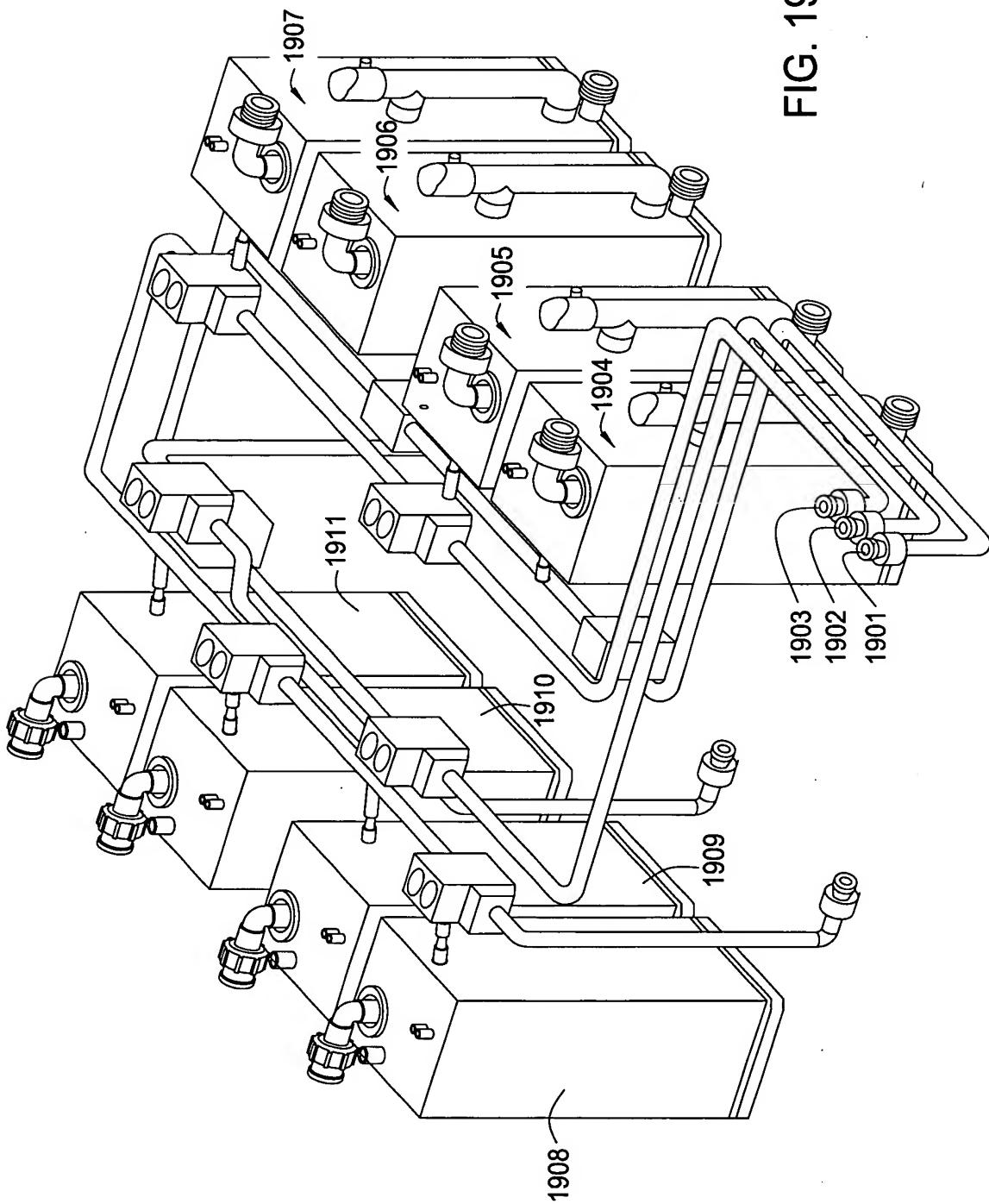
FIG. 17

FIG. 18



19/27

FIG. 19



20/27

2000

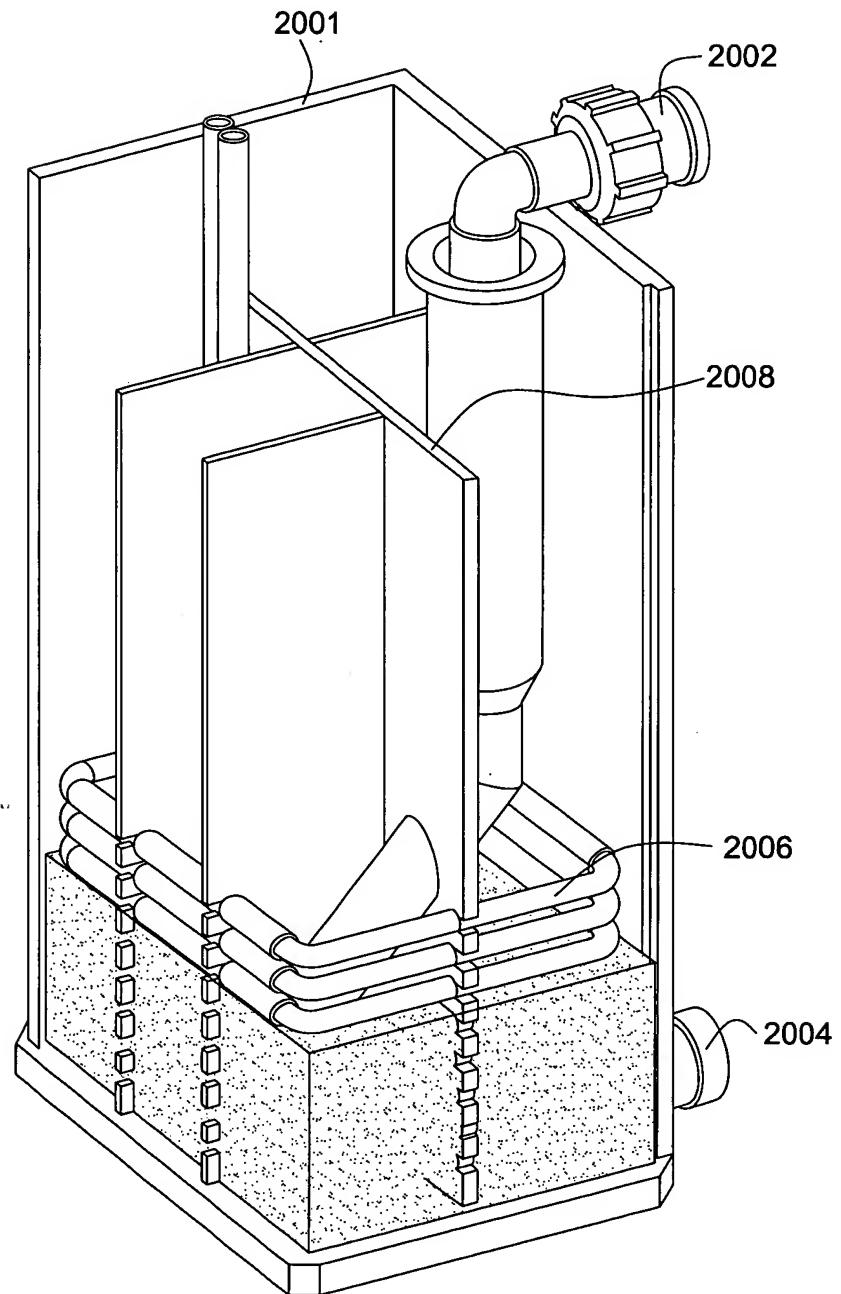


FIG. 20

21/27

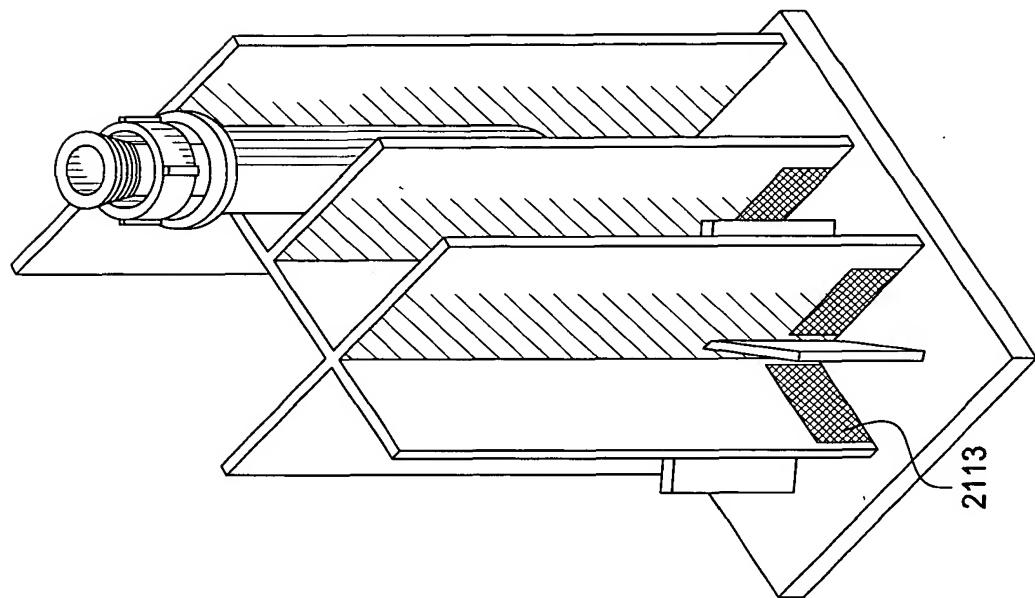


FIG. 22

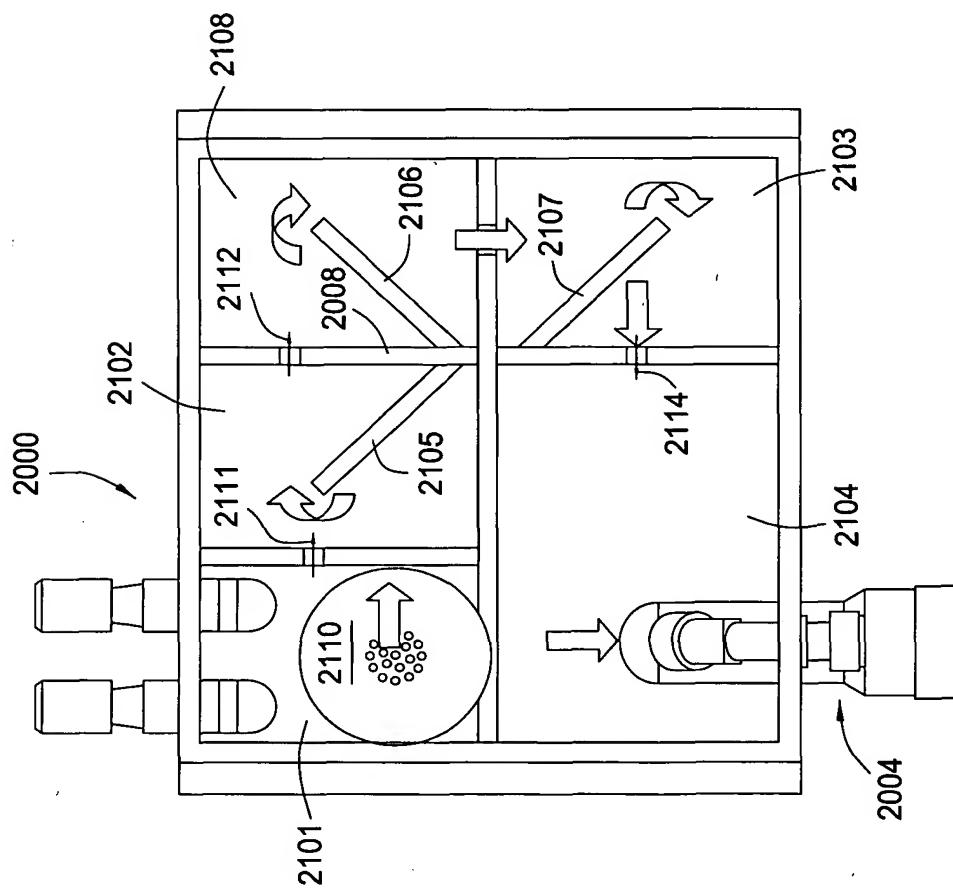
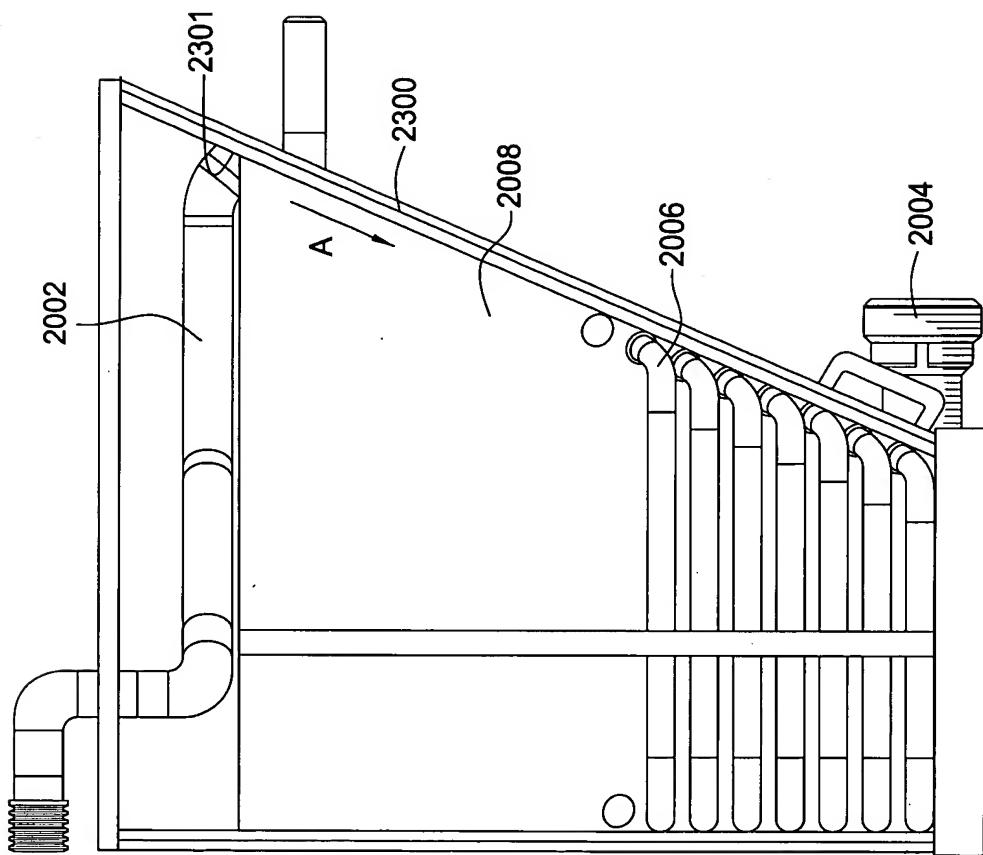


FIG. 21

22/27

FIG. 23



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23/27

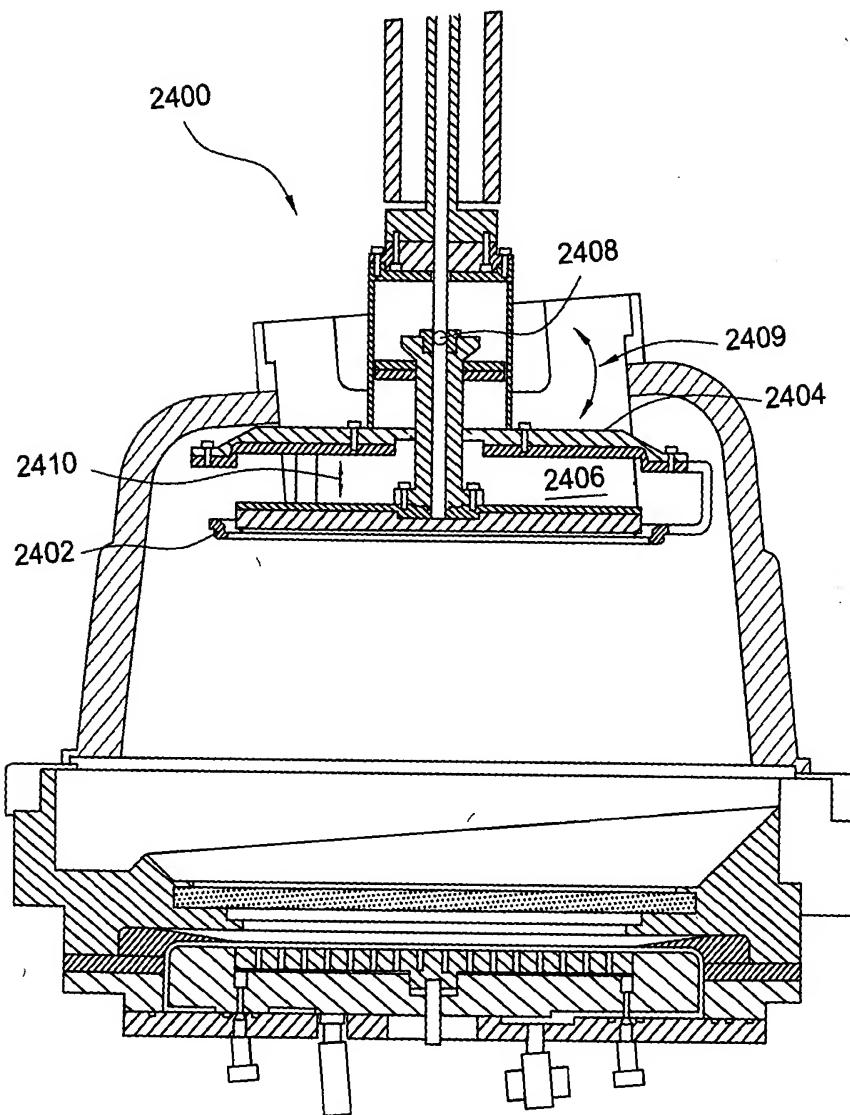


FIG. 24

24/27

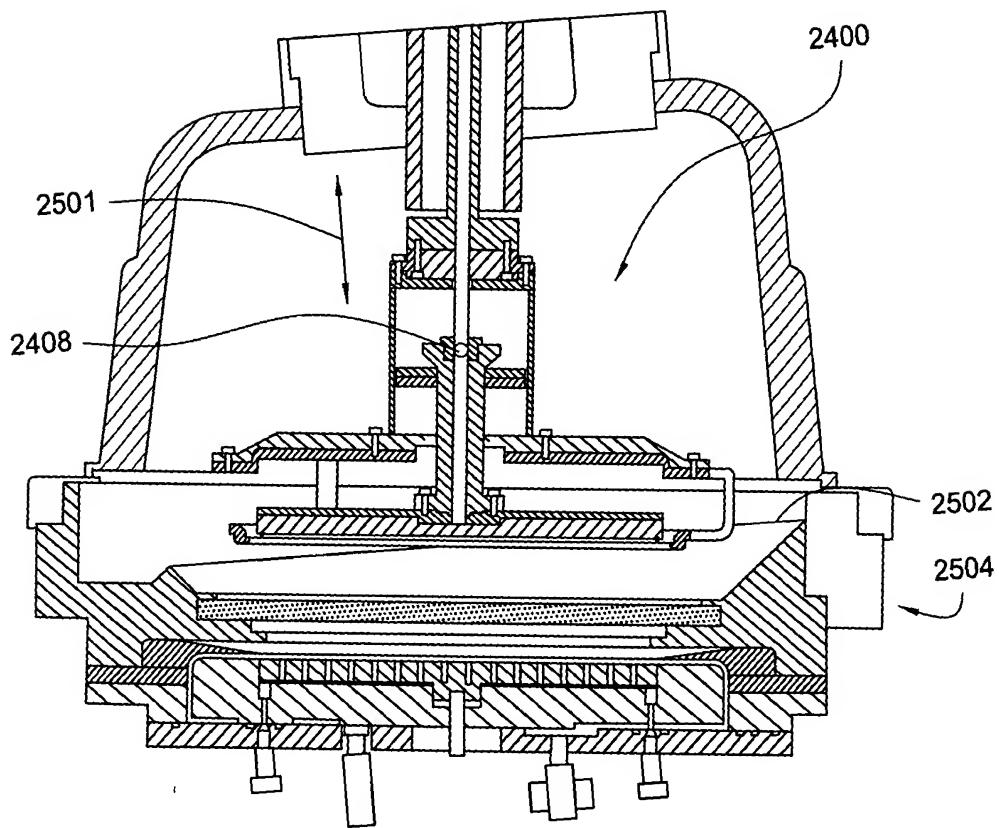


FIG. 25

25/27

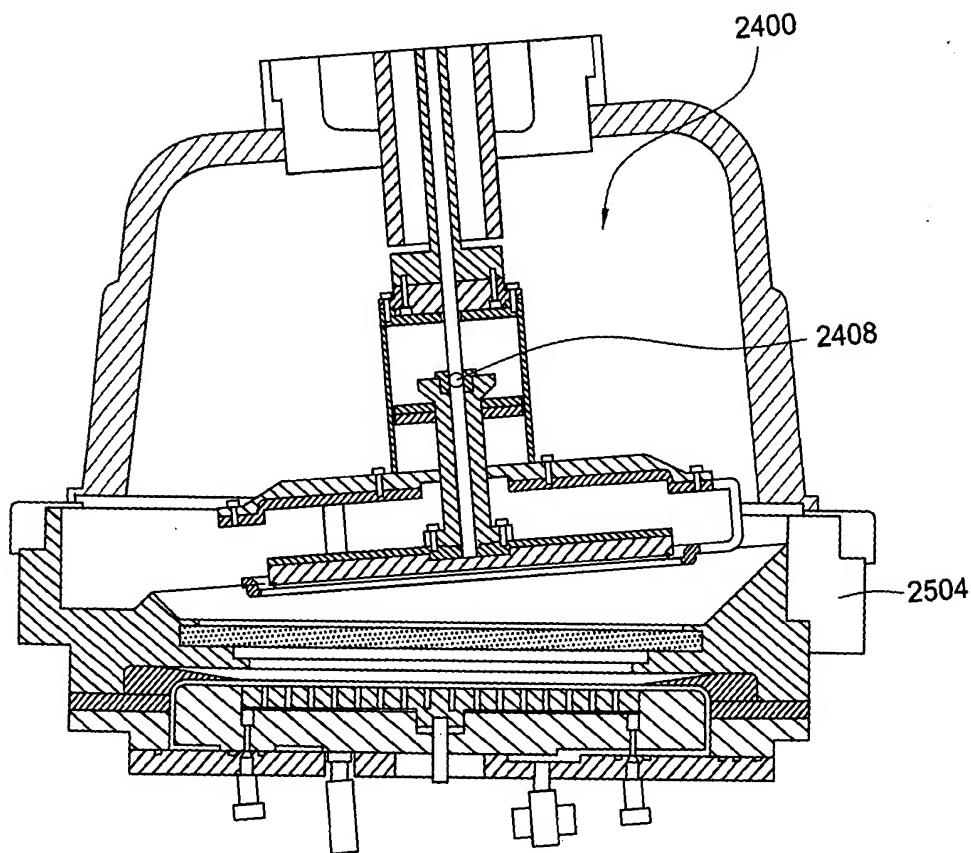


FIG. 26

ATTY DKT. No.: AMAT/7669.P1/CMP/ECP/RKK
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EXPRESS MAIL NO.: EV351031813US

26/27

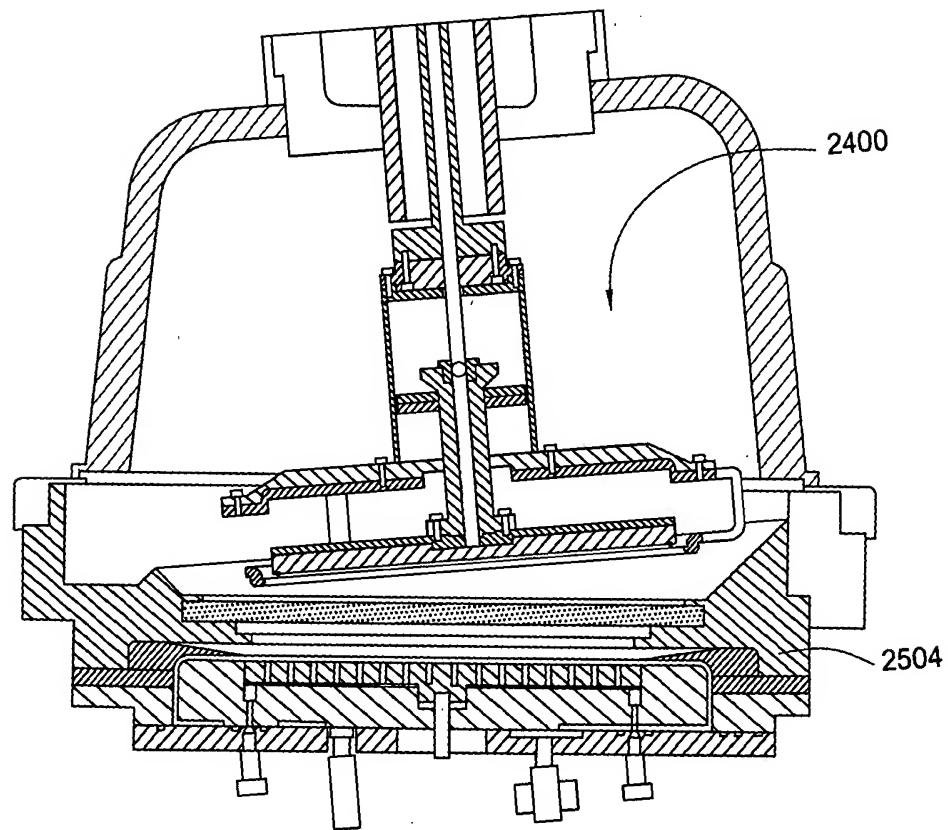


FIG. 27

